### KAMAYA OHM

Spec. No.: RLP-K-HTS-0001 /12

Date: 2022. 12. 31

## Data sheet

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

Style: RLP16,20,32,63, MLP20,63

# RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature:  $+5^{\circ}C \sim +35^{\circ}C$ Relative humidity:  $25\% \sim 75\%$ 

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

No: RLP-K-HTS-0001

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Title: METAL-PLATE CHIP RESISTOR; LOW OHM

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#### 1. Scope

1.1 This data sheet covers the detail requirements for metal-plate chip resistor; low ohm, style of RLP16, 20, 32, 63, MLP20, 63.

#### 1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014

#### 2. Classification

Type designation shall be the following form.

(Example)

RLP	63	K	R010	F	TE
1	2	3	4	5	6
Sty	/le				

1 Metal - plate chip resistor; low ohm

2 Size

RLP16	1608 size, 0.33W
RLP20	2012 size, 0.5W
RLP32	3216 size, 1W
RLP63	6332 size, 1W
MLP20	2012 size, 1W
MLP63	6332 size, 2W

#### 3 Temperature coefficient of resistance

N	±70×10 <sup>-6</sup> / °C
K	±100×10 <sup>-6</sup> / °C
(Doob)	±150×10 <sup>-6</sup> / °C
-(Dash)	±250×10 <sup>-6</sup> / °C

#### 4 Rated resistance

1L50	1.5mΩ
R002	2mΩ

#### 5 Tolerance on rated resistance

F	±1%
J	±5%

#### 6 Packaging form

TP	Paper taping
TE	Embossed taping

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#### 3. Rating

3.1 The ratings shall be in accordance with Table-1.

#### 3.1.1 RLP series

Table-1(1)

	Dated discipation		Temperature		Rated resistance	Tolerance on rated																	
Style	Rated dissipation (W)	Rated current (A)	resistance	(10 <sup>-6</sup> /°C)	$(m\Omega)$	resistance																	
		0.4	K	100																			
51.516	0.33	8.1	N	±70	- 5																		
RLP16			K	100																			
		5.7	N	±70	10																		
			K	100																			
		15.8	N	±70	2																		
			K	100																			
		11.1	N	±70	4																		
			K	100																			
		10.0	N	±70	5																		
			K																				
RLP20	0.5	9.1		100	6																		
			N	±70																			
		7.9	K	100	8																		
			N	±70	Ů																		
		7.4	K	100	9																		
		7.1	N	±70	•																		
		7.0	K	100	10																		
		7.0	N	±70	10																		
																			31.6	-(Standard)	±150	1	
		01.0	K	±100	'																		
		22.3	K	±100	2																		
		22.3	N	±70	] 2	F(±1%)																	
		18.2	K	±100	2																		
			N	±70	3																		
				15.8	K	±100	4	J(±5%)															
		15.8	N	±70	4																		
		444	K	±100	-																		
		14.1	N	±70	5																		
		40.0	K	±100	0																		
		12.9	N	±70	6																		
													44.0	K	±100	_							
		11.9	N	±70	7																		
DI Doo	1.0	44.4	K	±100	0																		
RLP32		11.1	N	±70	- 8																		
		40.5	K	±100	_	1																	
	1	10.5	N	±70	9																		
			K	±100	46																		
		10	N	±70	10																		
			K	±100	44																		
		9.5	N	±70	11																		
		_	K	±100																			
		9.1	N	±70	12																		
		_	K	±100																			
		8.7	N	±70	13																		
			K	±100																			
		8.4	N	±70	14																		
			K	±100																			
		8.1	N N		15																		
			IN	±70																			

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Table-1(2)

Style	Rated dissipation (W)	Rated current (A)	Temperature coefficient of resistance (10 <sup>-6</sup> / °C)		Rated resistance (mΩ)	Tolerance on rated resistance
	, ,		-(Standard)	±150	,	
	2.0	44.7	K	±100	1	
			N	±70		
		22.3	K	±100	2	
		22.3	N	±70	2	
		18.2	K	±100	3	
		10.2	N	±70	3	F(±1%) J(±5%)
		15.8	K	±100	4	
		10.0	N	±70	7	
	1.0	14.1	K	±100	5	
			N	±70	J	
		12.9	K	±100	6	
RLP63			N	±70	J	
			K	±100	7	
			N	±70	,	
		11.1	K	±100	8	
			N	±70		
		10.5	K	±100	9	
		10.0	N	±70		
		10	K	±100	10	
		10	N	±70		
		9.1	K	±100	12	
		9.1	N	±70		
		8.1	K	±100	15	
		5.1	N	±70		

#### 3.1.2 MLP series

Table-1(3)

	Table-1(3)								
Style	Rated dissipation	Rated current	Temperature coefficient of		Rated resistance	Tolerance on rated			
Otyle	(W)	(A)	resistance	(10 <sup>-6</sup> / °C)	$(m\Omega)$	resistance			
MLP20	1.0	10	K	100	10				
IVILI 20	1.0	10	N	±70	10				
		31.6	K	100	2				
		31.0	N	±70	2				
		25.8	K	100	3				
		23.0	N	±70	S	F(±1%) J(±5%)			
		22.3	K	100	4				
	2.0	22.3	N	±70	4				
		20	K	100	5				
			N	±70	5				
MLP63		2.0 18.2	K	100	6				
IVILI 00			N	±70	U				
		16.9	K	100	7				
		10.9	N	±70	ľ				
		15.8 14.9	K	100	8				
			N	±70	O				
			K	100	9				
			N	±70	3				
		14.1	K	100	10				
		14.1	N	±70	10				

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	1 1 2 12	
Style	Insulation voltage	Category temperature range
- 9 -	(V)	(°C)
RLP10		
RLP16		
RLP20		
RLP32	100	<i>–</i> 55∼+155
RLP63		
MLP20		
MLP63		

3.2 Climatic category

55/155/56 Lower category temperature –55 °C

Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long–term tests  $\pm 5\%$ -for short–term tests  $\pm 1\%$ 

#### 3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

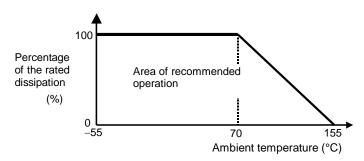


Figure-1 Derating curve

#### 3.5 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (
$$\Omega$$
)

#### 3.6 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

I: Rated current (A)
$$I = \sqrt{P / R}$$
P: Rated dissipation (W)
R: Rated resistance ( $\Omega$ )

The rated current shall be corresponding to rated voltage.

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#### 4. Packaging form

The standard packaging form shall be in accordance with Table-2.

#### Table-2

	Symbol	Packaging form		Standard packaging quantity / units	Application
ĺ	TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RLP16, 20, 32, MLP20
ĺ	TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RLP63, MLP63

#### 5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

#### 5.1.1 RLP series

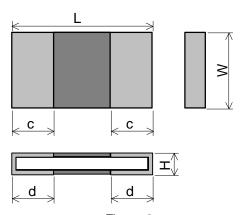
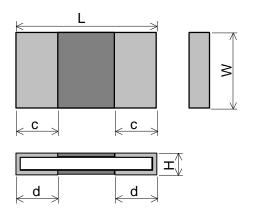


Figure-2

Table–3(1) Unit: mm

		iu	JIC-3( I)		Of III. 11II11		
Style	Rated resistance (m $\Omega$ )	L	W	Н	С	d	
RLP16	5	1.6±0.1	0.8±0.1	0.35±0.10	0.2±0.1	0.6±0.1	
KLF 10	10	1.0±0.1	0.0±0.1	0.3±0.1	0.2±0.1	0.3±0.1	
	2			0.22±0.10	0.35±0.10	0.55±0.20	
	4			0.35±0.10	0.35±0.10	0.75±0.20	
	5			0.35±0.10	0.35±0.10	0.6±0.2	
RLP20	6	2.0±0.15	1.25±0.15	0.35±0.10	0.35±0.10	0.47±0.20	
	8			0.22±0.10	0.35±0.10	0.6±0.2	
	9			0.22±0.10	0.35±0.10	0.52±0.20	
	10			0.22±0.10	0.35±0.10	0.47±0.20	
	1			0.32±0.15	1.1±0.25	1.1±0.25	
	2			0.32±0.15	0.5±0.25	0.5±0.25	
	3			0.35±0.10	0.7±0.25	1.3±0.25	
	4			0.35±0.10	1.1±0.25	1.1±0.25	
	5			0.35±0.10	1.0±0.25	1.0±0.25	
	6			0.35±0.10	0.85±0.25	0.85±0.25	
	7			0.35±0.10	0.7±0.25	0.7±0.25	
RLP32	8	3.2±0.15	1.6±0.15	0.35±0.10 0.3±0.1	0.6±0.25	0.6±0.25	
112102	9	0.2_0.10	110_0110		0.75±0.25	0.75±0.25	
	10			0.28±0.10	0.5±0.25	0.5±0.25	
	11			0.28±0.10	0.5±0.25	0.5±0.25	
	12			0.22±0.10	0.65±0.25	0.65±0.25	
	13			0.22±0.10	0.65±0.25	0.65±0.25	
	14	]		0.22±0.10	0.55±0.25	0.55±0.25	
	15			0.22±0.10	0.5±0.25	0.5±0.25	

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		Tak	ole-3(2)			Unit: mm
Style	Rated resistance (mΩ)	L	W	Н	С	d
	1		3.2±0.25	0.38±0.15	2.2±0.25	2.2±0.25
	2			0.38±0.15	1.1±0.25	1.1±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
	4			0.35±0.15	2.2±0.25	2.2±0.25
	5			0.34±0.15	1.95±0.25	1.95±0.25
DI Dea	6	62.025		0.34±0.15	1.75±0.25	1.75±0.25
RLP63	7	6.3±0.25	3.1±0.25	0.35±0.15	1.4±0.25	1.4±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10	]		0.23±0.15	1.75±0.25	1.75±0.25
	12			0.23±0.15	1.4±0.25	1.4±0.25
	15			0.23+0.15	0.95+0.25	0.95+0.25

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#### 5.1.2 MLP series

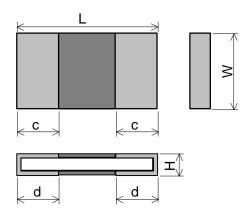


Table-3(3)

Unit: mm

Style	Rated resistance (m $\Omega$ )	L	W	Н	С	d
MLP20	10	2.0±0.15	1.25±0.15	0.22±0.10	0.33±0.15	0.47±0.20
	2			0.58±0.15	2.2±0.25	2.2±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
	4			0.34±0.15	2.2±0.25	2.2±0.25
	5		3.1±0.25	0.51±0.15	1.1±0.25	1.1±0.25
MLP63	6	6.3±0.25		0.5±0.15	1.1±0.25	1.1±0.25
	7			0.5±0.15	0.6±0.25	0.6±0.25
	8			0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10			0.35±0.15	0.5±0.25	0.5±0.25

#### 5.2 Net weight (Reference)

, ,							
Style	Rated resistance (m $\Omega$ )	Net weight (mg)					
RLP16	5,10	2					
RLP20	2, 4 to 6 , 8 to 10	3					
RLP32	1 to 3	12					
NLF32	4 to 15	11					
RLP63	1,2	47					
KLF03	3 to 10,12 15	43					
MLP20	10	3					
MLP63	2 to 10	60					

#### 6. Marking

The Rated resistance of RLP16 should not be marked standard.

#### 6.1 RLP63, MLP63

The rated resistance shall be marked in 4 characters consisting of 3 figures and a letter and marked on over coat side.

(Example) "R010"  $\rightarrow$  0.01 [ $\Omega$ ]  $\rightarrow$  10 [m $\Omega$ ]

"1L50"  $\rightarrow$  0.0015 [ $\Omega$ ]  $\rightarrow$  1.5 [m $\Omega$ ]

#### 6.2 RLP20, 32, MLP20

The rated resistance shall be marked in combination of two figures and underlines and marked on over coat side.

(Example) " $\underline{05}$ "  $\rightarrow$  0.005 [ $\Omega$ ]  $\rightarrow$  5 [m $\Omega$ ]

" $\underline{10}$ "  $\rightarrow$  0.01 [ $\Omega$ ]  $\rightarrow$  10 [m $\Omega$ ]

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#### 7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items		ا able– 4 کondition of test (	` '	01_1)		Performance requirements
1	Visual examination	Sub-clause			As in 4.4.1		
'	Visual examination		e 4.4. i y visual examina		The marking shall be legible, as		
		Criecked b	y visuai examina	iuOi i.			checked by visual examination.
2	Dimension	Sub-claus	<u> </u>				As specified in Table–3 of this
_		Sub-clausi	5 4.4.2				specification.
	Resistance	Resistance	value shall be	measure	ed by m	ountina	As in 4.5.2
			te of the following			· · · · · · · · · · · · · · · · · · ·	The resistance value shall
			b       a	5			correspond with the rated
		Current	Curr				resistance taking into account the
		terminal	term	inal	_		specified tolerance.
		Me	√ oltage terminal		_:Copper □:Solder		
		Į vo	ntage terriiriai				
			I 5 · .		Uni	t:mm	
		Style	Resistance	а	b	С	
			value(mΩ)	0.0	0.0		
		RLP16	5 10,	0.6 1.0	0.8	0.9	
			2	0.5	1.1		
		RLP20	4 to 6, 8 to 10	0.8	0.95	1.36	
			1	1.0	1.45		
			2	2.1	0.9		
		DI DOG	3	0.8	1.55	4 -	
		RLP32	4	1.0	1.45	1.7	
			5 and 6	1.4	1.25		
			7 to 15	2.1	0.9		
			1	1.5	3.0	4.0	
			2	4.0	1.8		
		RLP63	3, 4	1.8	2.9	3.5	
			5	2.4	2.6	0.0	
		N. Doc	6 to 10,12,15	4.0	1.8	4.00	
		MLP20	10	0.8	0.95	1.36	
		MLP63	2 to 4	1.8 4.0	2.9 1.8	3.5	
		Thiston	5 to 10				
		4-Terminal	of copper clad: 0				
			ent current: 1(A)				
		Note: The					
			ohm Mater (1A)				
		CORPOR		J. 7 J. 11	. 525 101		

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#### Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
3	Voltage proof	Sub-clause 4.7	No breakdown or flash over
		Method: 4.6.1.4(See Figure-5)	
		Test voltage: Alternating voltage with a peak value	
		of 1.42 times the insulation voltage.	
		Duration: 60 s±5 s	
		Insulation resistance	R≥1 GΩ
		Test voltage: Insulation voltage	_
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
-		Without aging	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2 s.	coating.
		Bath temperature: 235 °C±5 °C	- oodan igi
		Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
3	IVIOUITIIIII	Substrate material: Epoxide woven glass	
	Overload	Test substrate: RLP16: Figure–3–1	
	(in the mounted state)	RLP20, MLP20 Figure–3–2	
	(in the mounted state)	RLP32 Figure–3–3	
		RLP63, MLP63 Figure-3-4	
		Sub-clause 4.13	
		The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s	No visible demage
		Visual examination	No visible damage
	Solvent resistance of the	Resistance	$\Delta R \le \pm 1\%$
		Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure 4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3mm(RLP16, 20, 32, MLP20)	
		1 mm(RLP63, MLP63)	
		Resistance	ΔR ≤ ±1%
	Final measurements	Sub-clause 4.33.6	
		Visual examination	No visible damage
		viodai ondifiliation	J -

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#### Table-4(3)

	1able-4(3)									
No	Test items		ns	Condition of test (JIS C 5201–1)	Performance requirements					
7	Resistance heat	to	soldering	Sub-clause 4.18 (JEITA RC-2144 2.3.2) Substrate material: Epoxide woven glass Test substrate: Figure-3-1 T1:Pre-heat minimum temp.:150±5 °C T2:Pre-heat maximum temp.:180±5 °C T3:Soldering temp.:220 °C T4:Peak temp.:260 °C t1:Pre-heat duration:120±5 s t2:Soldering duration:60 to 90 s t3:Peak duration(T4-5°C):20 to 40 s Pre-reflow soldering: 1 time (Initial measurements) Reflow soldering: 3 times	renormance requirements					
	Component resistance		solvent	Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 2 Recovery: 48 h Visual examination Resistance	No visible damage $\Delta R \leq \pm 1\%$ No visible damage $\Delta R \leq \pm 1\%$					
8	Mounting			Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3–1						
	Adhesion			Sub-clause 4.32 Force: 5 N Duration: 10 s±1 s Visual examination	No visible damage					
	Rapid chang	e ter	mperature	Sub-clause 4.19 Lower category temperature:-55 °C Upper category temperature:+155 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination Resistance	No visible damage ΔR ≤ ±1%					

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#### Table-4(4)

	<u> </u>	1abic 4(4)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	-Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4.23.7	
		The applied current shall be the rated current.	
		Duration: 1 min.	No visible damage
		Visual examination	$\Delta R \le \pm 5\%$
		Resistance	AIX = 10 /0
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: RLP16: Figure–3–1	
		RLP20, MLP20 Figure-3-2	
		RLP32 Figure–3–3	
	F 1 170.00	RLP63, MLP63 Figure-3-4	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h on	
		and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	No visible damage
		Visual examination	$\Delta R \le \pm 5\%$
		Resistance	∆IX ≥ ±J /0
11	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Madaga at a st	Test substrate: Figure–3–1	
	Variation of resistance with	Sub-clause 4.8	As in Table–1
	temperature	+20 °C / +155 °C	

## **KAMAYA OHM**

No: RLP-K-HTS-0001 /12

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#### Table-4(5)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1	
	Damp heat, steady state	Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination Resistance	No visible damage Legible marking ΔR ≤ ±5%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table-4
	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1	
	Endurance at upper category temperature	Sub-clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h:	No visible damage
		Visual examination Resistance	$\Delta R \le \pm 5\%$

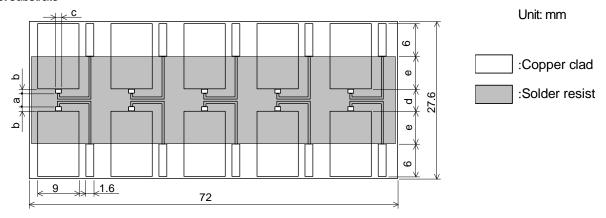
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#### 8. Test substrate



Style	Rated resistance (m $\Omega$ )	а	b	С	d	е	
RLP16	5	0.6	0.9	0.9	2.2	6.2	
KLF10	10	1.0	0.6	0.9	2.2	0.2	
DI DOO	2	0.5	1.1	1.26	2.7	E OE	
RLP20	4 to 6, 8 to 10	8.0	0.95	1.36	2.7	5.95	
	1	1.0	1.45				
	2	2.1	0.9			5.35	
DI DOO	3	0.8	1.55	7 17	3.9		
RLP32	4	1.0	1.45	1.7			
	5 and 6	1.4	1.25				
	7 to 15	2.1	0.9				
	1	1.5	3.05				
	2	4.0	1.8				
RLP63	3, 4	1.8	2.9	3.5	7.6	3.5	
	5	2.4	2.6				
	6 to 10,12,15	4.0	1.8				
MLP20	10	0.8	0.95	1.36	2.7	5.95	
MI DCO	2 to 4	1.8	2.9	2.5	7.0	0.5	
MLP63	5 to 10	4.0	1.8	3.5	7.6	3.5	

Figure-3-1 RLP, MLP TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

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Unit: mm
:銅箔パターン
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Style	Rated resistance (m $\Omega$ )	а	b	С	d	е
RLP20	2	0.5	1.1			
KLP20	4 to 6, 8 to 10	0.8	0.95	1.36	2.7	5.95
MLP20	10	0.8	0.95			

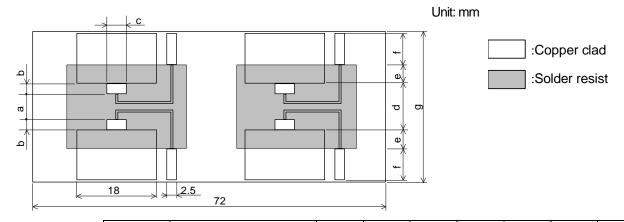
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Figure-3-2 RLP20, MLP20 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

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Style	Rated resistance (m $\Omega$ )	а	b	С	d	е	f	g
	1	1.0	1.45				11.68	39
	2	2.1	0.9				6.0	27.6
DI DOO	3	0.8	1.55	47	2.0	3.9 5.35	0.0	27.0
RLP32	4	1.0	1.45	1.7	3.9		11.68	39
	5 and 6	1.4	1.25				6.0	27.6
	7 to 15	2.1	0.9				6.0	27.6

Figure-3-3 RLP32, MLP32 TEST SUBSTRATE

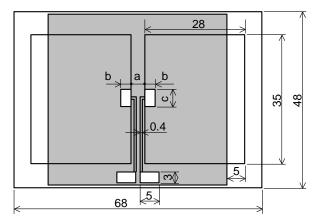
Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

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Unit: mm								
:Copper clad								
:Solder resist								
Style	Rated resistance $(m\Omega)$	а	b	С				
	1	2.0	3.0	4.0				
	2	4.0	1.8					
RLP63	3, 4	1.8	2.9	2.5				
	5	2.4	2.6	3.5				
	6 to 10,12,15	4.0	1.8					
MI Dea	2 to 4	1.8	2.9	3.5				
MLP63	5 to 10	4.0	1.8	3.3				

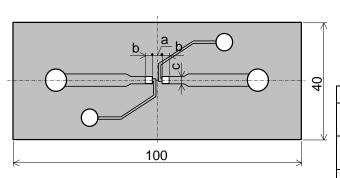
Figure-3-4 RLP63, MLP63 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

Remark: In the case of connection by connector, the connecting terminals are gold plated.

However, the plating is not necessary when the connection is made by soldering.

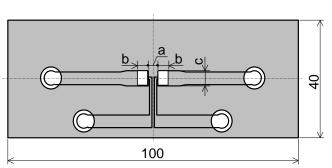


Unit: mm
:Copper clad
:Solder resist

Style	Rated resistance (m $\Omega$ )	а	b	С
RLP16	5	0.6	0.9	0.9
	10	1.0	0.6	
RLP20	2,3	0.5	1.1	1.36
	4 to 6, 8 to 10	8.0	0.95	
RLP32	1	1.0	1.45	1.7
	2	2.1	0.9	
	3	8.0	1.55	
	4	1.0	1.45	
	5 and 6	1.4	1.25	
	7 to 15	2.1	0.9	
MLP20	10	0.8	0.95	1.36

RLP, MLP BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

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Ĺ	Jnit: mm
	:Copper clad
	:Solder resist

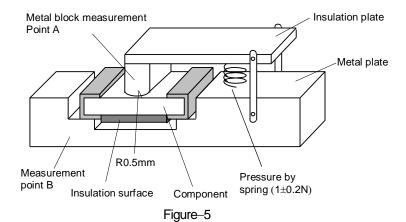
Style	Rated resistance (m $\Omega$ )	а	b	С
RLP63	1	1.5	3.05	4.0
	2	4.0	1.8	3.5
	3, 4	1.8	2.9	
	5	2.4	2.6	
	6 to 10,12,15	4.0	1.8	
MLP63	2 to 4	1.8	2.9	3.5
	5 to 10	4.0	1.8	

RLP 63, MLP63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Figure-4

Remark. Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



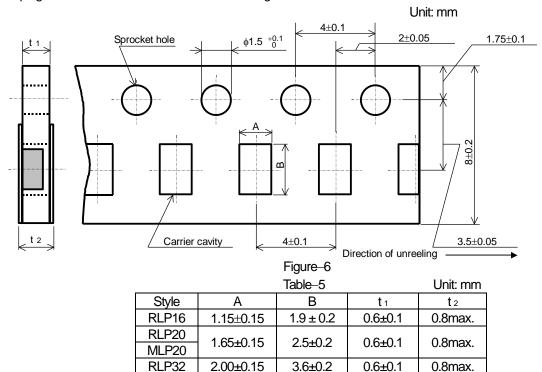
Product specification contained in this data sheet are subject to change at any time without notice.

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#### 9. Taping

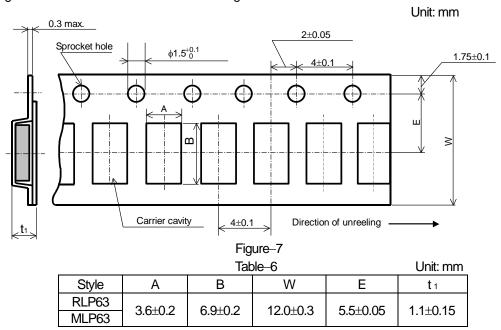
- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.



#### 9.2.2 Embossed taping (12mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-7 and Table-6.



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- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RLP16, 20, 32, MLP20: Figure–8, RLP63, MLP63: Figure–9.
- 6). When the tape is bent with the minimum radius for (RLP16, 20, 32, MLP20: 25mm, RLP63, MLP63: 30mm) the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

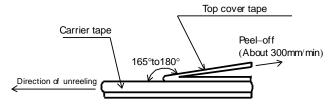


Figure-8

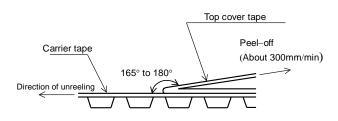


Figure-9

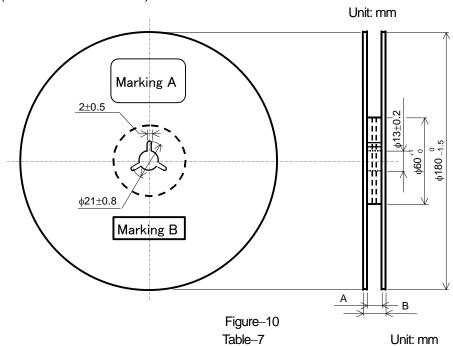
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#### 9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-10 and Table-7. Plastic reel (Based on EIAJ ET-7200C)

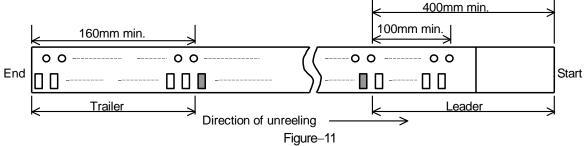


В Note Α

Style 11.4±1.0 Injection molding RLP16, 20, 32, MLP20  $9^{+1.0}_{0}$ 13±1.0 Vacuum forming RLP63, MLP63 13 +1.0 17±1.0 Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

#### 9.4 Leader and trailer tape.



#### 10. Marking on package

The label of a minimum package shall be legibly marked with follows.

#### 10.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Lot number (3) Quantity (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)

## 单击下面可查看定价,库存,交付和生命周期等信息

## >>Kamaya(釜屋电机)